

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of Applicants:

Beaman et al.

Serial No.: 09/382,834

Filed: August 25, 1999

For: HIGH DENSITY INTEGRATED CIRCUIT APPARATUS,
TEST PROBE AND METHODS OF USE THEREOF

Date: May 7, 2001

Group Art Unit: 2858

Examiner: V. Nguyen

Docket No.: YO993-028BX

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Assistant Commissioner for Patents
Washington, D. C. 20231

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Dr. Daniel P. Morris, Esq.
Reg. No. 32,053

AMENDMENT

In response to Office Action dated 11-7-2000, please consider the following:

IN THE ABSTRACT

[The present invention is directed to a] A high density test probe which provides [a means] an apparatus for testing a high density and high performance integrated circuits in wafer form or as discrete chips. The test probe is formed from a dense array of elongated electrical conductors which are embedded in an compliant or high modulus elastomeric material. A standard packaging substrate, such as a ceramic integrated circuit chip packaging substrate is used to provide a space transformer. Wires are

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